

# MATERIAL DECLARATION SHEET



Material Number	SRP2010DPA Series			
Product Line	Shielded SMD Power Inductor			
Compliance Date	2021 / 04 / 12			
RoHS Compliant	YES	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Amorphous Powder	Alloy Amorphous Powder	14.08	Iron	7439-89-6	86.845	51.638	59.46
				Silicon	7440-21-3	6.700	3.984	
				Chromium -non-hexavalent	7440-47-3	2.500	1.486	
				Boron	7440-42-8	2.500	1.486	
				Carbon	7440-44-0	0.700	0.416	
				Manganese	7439-96-5	0.700	0.416	
				Phosphorus	7723-14-0	0.040	0.024	
				Sulfur	7704-34-9	0.015	0.009	
2	Copper Wire	Flat Copper Wire	7.00	Copper	7440-50-8	92.500	27.344	29.56
				Acryl Resin	confidential	5.0	1.478	
				Polyamide Resin	63428-83-1	2.5	0.739	
3	Epoxy Resin	Epiclone N-670	0.59	Formaldehyde, polymer with (chloromethyl) oxirane and 2-methylphenol	29690-82-2	100.0	2.492	2.49
4	Hardening	Phenolite TD-2131E	0.311	Phenolic resin	9003-35-4	100.0	1.313	1.31
5	Silver Paste	CA-103	1.335	Silver	7440-22-4	82.4	4.647	5.64
				Resin	confidential	17.6	0.993	

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6	Plating	Ni Plating	0.364	Nickel	7440-02-0	20.0	0.307	1.54
		Sn Plating		Tin	7440-31-5	80.0	1.230	
	Total weight	23.68						

**This Document was updated on: 2021/04/12**

**Important remarks:**

1. It is the responsibility of the user to verify they are accessing the latest version.